

ABSTRACT OF THE DISCLOSURE

A solder bump fabrication method and apparatus. First, a printed circuit board, having a plurality of devices, is provided.

5 A material is formed on the printed circuit board, and it is disposed between pins of the devices to prevent the devices from short-circuiting due to the solder bumps. Then, the solder bumps are formed on the pins of the devices so that the devices are fixed on the printed circuit board. The printed circuit board
10 is passed through an infrared oven to melt the solder bumps. The material separates the solder bumps attached to the pins of the devices so that the devices are prevented from short-circuiting.